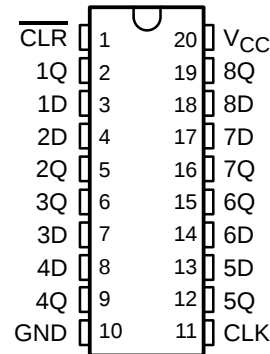


SN54AHC273, SN74AHC273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

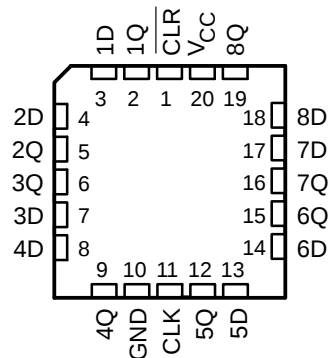
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- Operating Range 2-V to 5.5-V V_{CC}
- Contain Eight Flip-Flops With Single-Rail Outputs
- Direct Clear Input
- Individual Data Input to Each Flip-Flop
- Applications Include:
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)

SN54AHC273 ... J OR W PACKAGE
SN74AHC273 ... DB, DGV, DW, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AHC273 ... FK PACKAGE
(TOP VIEW)



description/ordering information

These circuits are positive-edge-triggered D-type flip-flops with a direct clear (CLR) input.

Information at the data (D) inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When CLK is at either the high or low level, the D input has no effect at the output.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AHC273N	SN74AHC273N
	SOIC – DW	Tube	SN74AHC273DW	AHC273
		Tape and reel	SN74AHC273DWR	
	SOP – NS	Tape and reel	SN74AHC273NSR	AHC273
	SSOP – DB	Tape and reel	SN74AHC273DBR	HA273
	TSSOP – PW	Tube	SN74AHC273PW	HA273
		Tape and reel	SN74AHC273PWR	
–55°C to 125°C	TVSOP – DGV	Tape and reel	SN74AHC273DGVR	HA273
	CDIP – J	Tube	SNJ54AHC273J	SNJ54AHC273J
	CFP – W	Tube	SNJ54AHC273W	SNJ54AHC273W
	LCCC – FK	Tube	SNJ54AHC273FK	SNJ54AHC273FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

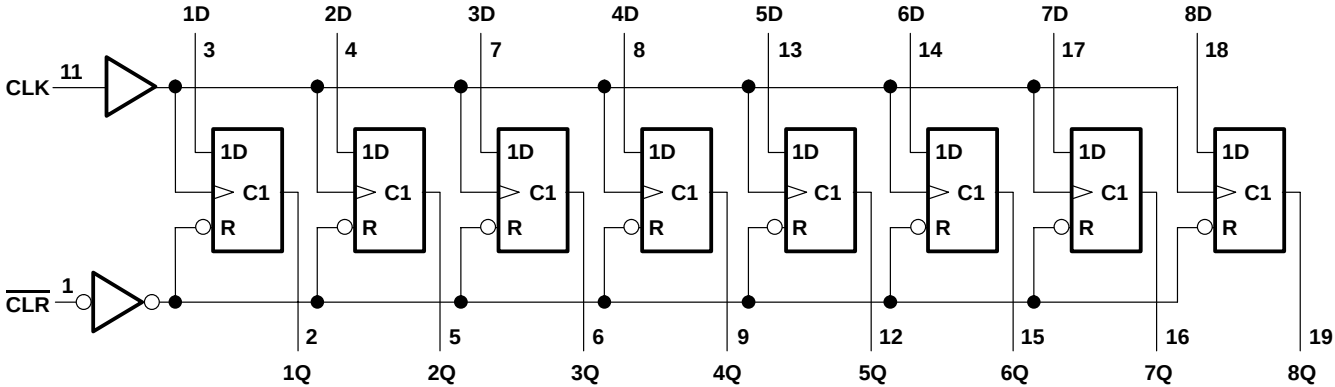
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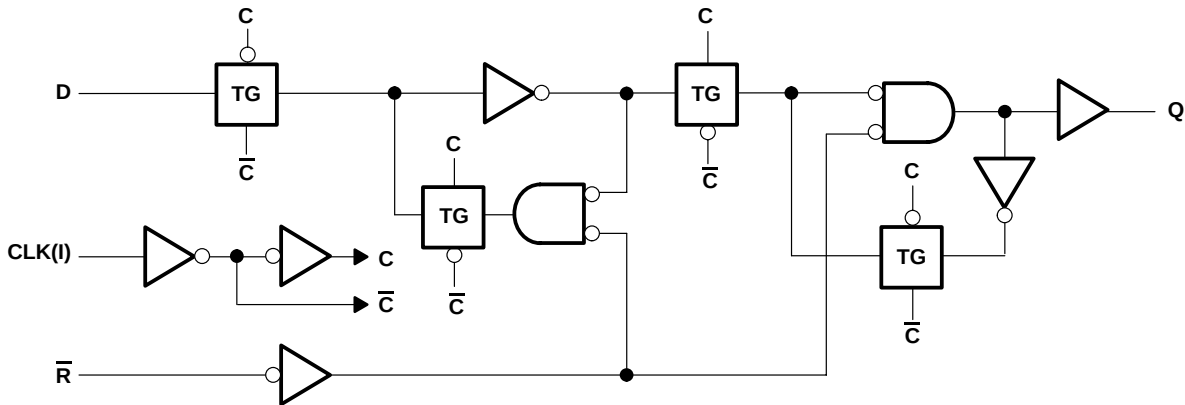
FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT Q
$\overline{\text{CLR}}$	CLK	D	
L	X	X	L
H	$\uparrow$	H	H
H	$\uparrow$	L	L
H	L	X	Q_0

logic diagram (positive logic)



logic diagram, each flip-flop (positive logic)



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3

SN54AHC273, SN74AHC273

OCTAL D-TYPE FLIP-FLOPS

WITH CLEAR

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHC273		SN74AHC273		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = –50 µA	2 V	1.9			1.9		1.9		V
		3 V	2.9			2.9		2.9		
		4.5 V	4.4			4.4		4.4		
	I _{OH} = –4 mA	3 V	2.58			2.48		2.48		
	I _{OH} = –8 mA	4.5 V	3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 µA	2 V			0.1		0.1		0.1	V
		3 V			0.1		0.1		0.1	
		4.5 V			0.1		0.1		0.1	
	I _{OL} = 4 mA	3 V			0.36		0.5		0.44	
	I _{OL} = 8 mA	4.5 V			0.36		0.5		0.44	
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1*		±1	µA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		40		40	µA
C _i	V _I = V _{CC} or GND	5 V			2.5	10			10	pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		SN54AHC273				SN74AHC273				UNIT
		T _A = 25°C		MIN	MAX	T _A = 25°C		MIN	MAX	
		MIN	MAX			MIN	MAX			
t _w	Pulse duration	CLR low	5	6	5	6	ns			
		CLK high or low	5	6.5	5	6.5				
t _{su}	Setup time	Data before CLK↑	5.5	6.5	5.5	6.5	ns			
		CLR before CLK↑	2.5	2.5	2.5	2.5				
t _h	Hold time, data after CLK↑		1.5	2	1	1	ns			

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		SN54AHC273				SN74AHC273				UNIT
		T _A = 25°C		MIN	MAX	T _A = 25°C		MIN	MAX	
		MIN	MAX			MIN	MAX			
t _w	Pulse duration	CLR low	5	5	5	5	5	5	ns	
		CLK high or low	5	5	5	5	5			
t _{su}	Setup time	Data before CLK↑	4.5	4.5	4.5	4.5	4.5	4.5	ns	
		CLR before CLK↑	2	2	2	2	2			
t _h	Hold time, data after CLK↑		1.5	2	1	1	1	1	ns	



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SN54AHC273, SN74AHC273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54AHC273		SN74AHC273		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\max}$			$C_L = 15 \text{ pF}$	75*	120*		65*		65		MHz
			$C_L = 50 \text{ pF}$	50	75		45		45		
t_{PHL}	$\overline{\text{CLR}}$	Q	$C_L = 15 \text{ pF}$		8.9*	13.6*	1*	16*	1	16	ns
t_{PLH}	CLK	Q	$C_L = 15 \text{ pF}$		8.7*	13.6*	1*	16*	1	16	ns
t_{PHL}					8.7*	13.6*	1*	16*	1	16	
t_{PHL}	$\overline{\text{CLR}}$	Q	$C_L = 50 \text{ pF}$		11.4	17.1	1	19.5	1	19.5	ns
t_{PLH}	CLK	Q	$C_L = 50 \text{ pF}$		11.2	17.1	1	19.5	1	19.5	ns
t_{PHL}					11.2	17.1	1	19.5	1	19.5	
$t_{\text{sk}}(0)$			$C_L = 50 \text{ pF}$			1.5**				1.5	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54AHC273		SN74AHC273		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\max}$			$C_L = 15 \text{ pF}$	120*	165*		100*		100		MHz
			$C_L = 50 \text{ pF}$	80	110		70		70		
t_{PHL}	$\overline{\text{CLR}}$	Q	$C_L = 15 \text{ pF}$		5.2*	8.5*	1*	10*	1	10	ns
t_{PLH}	CLK	Q	$C_L = 15 \text{ pF}$		5.8*	9*	1*	10.5*	1	10.5	ns
t_{PHL}					5.8*	9*	1*	10.5*	1	10.5	
t_{PHL}	$\overline{\text{CLR}}$	Q	$C_L = 50 \text{ pF}$		6.7	10.5	1	12	1	12	ns
t_{PLH}	CLK	Q	$C_L = 50 \text{ pF}$		7.3	11	1	12.5	1	12.5	ns
t_{PHL}					7.3	11	1	12.5	1	12.5	
$t_{\text{sk}}(0)$			$C_L = 50 \text{ pF}$			1**				1	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.

noise characteristics, $V_{CC} = 5 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 4)

PARAMETER		SN74AHC273			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.7		V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		-0.7		V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		4.7		V
$V_{IH(D)}$	High-level dynamic input voltage		3.5		V
$V_{IL(D)}$	Low-level dynamic input voltage			1.5	V

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^\circ\text{C}$

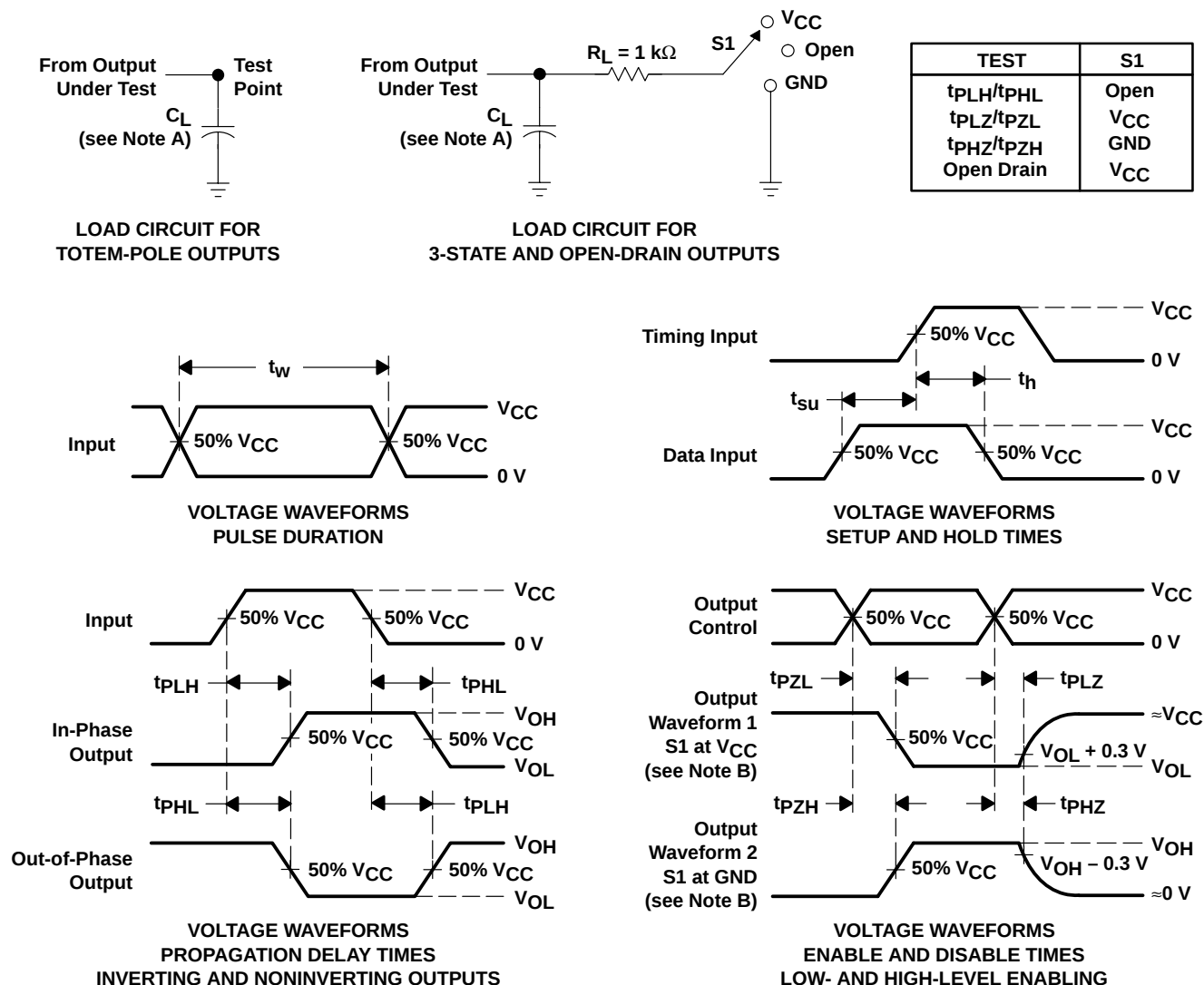
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load, $f = 1 \text{ MHz}$	31	pF



SN54AHC273, SN74AHC273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

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PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

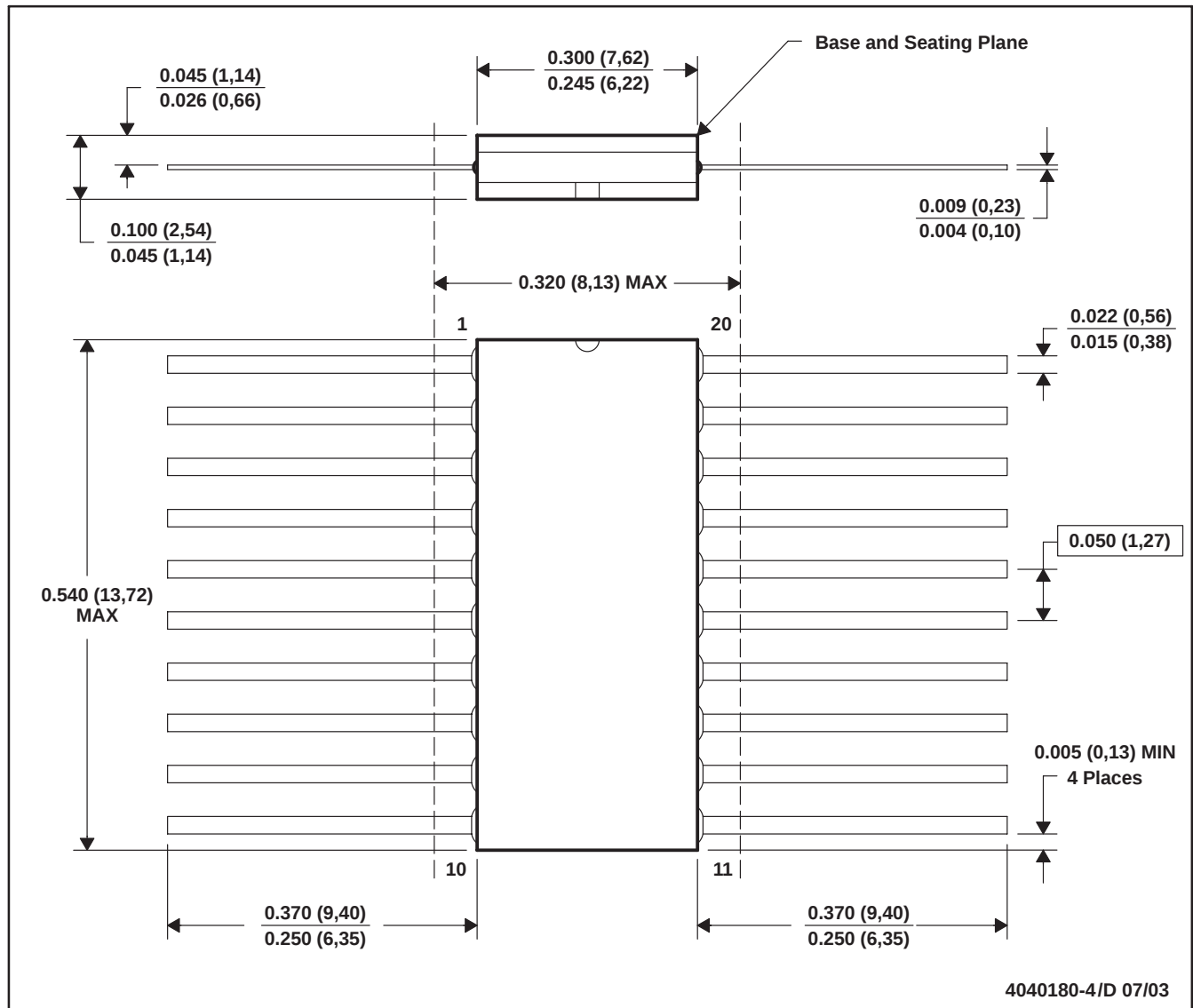


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

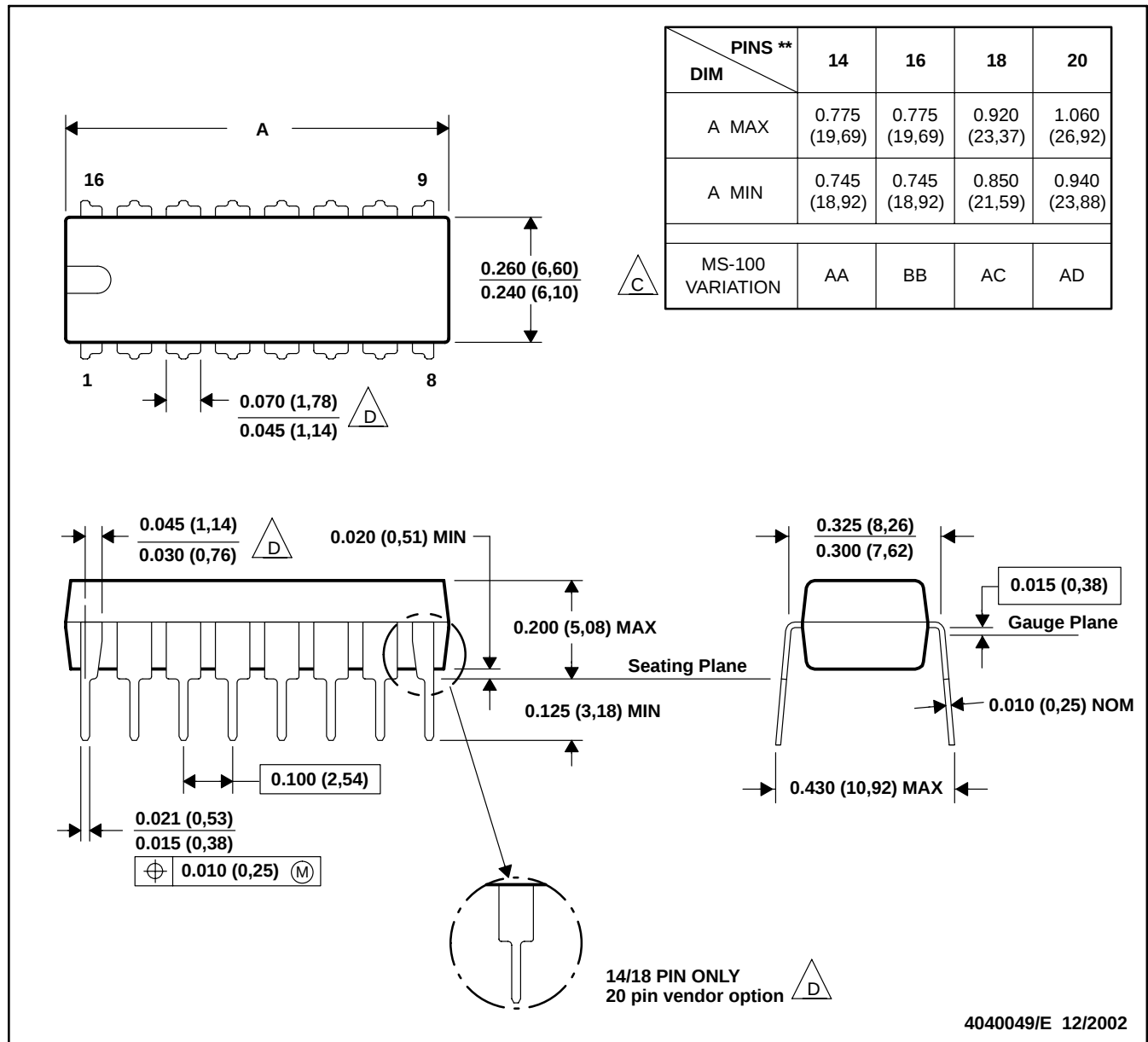


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

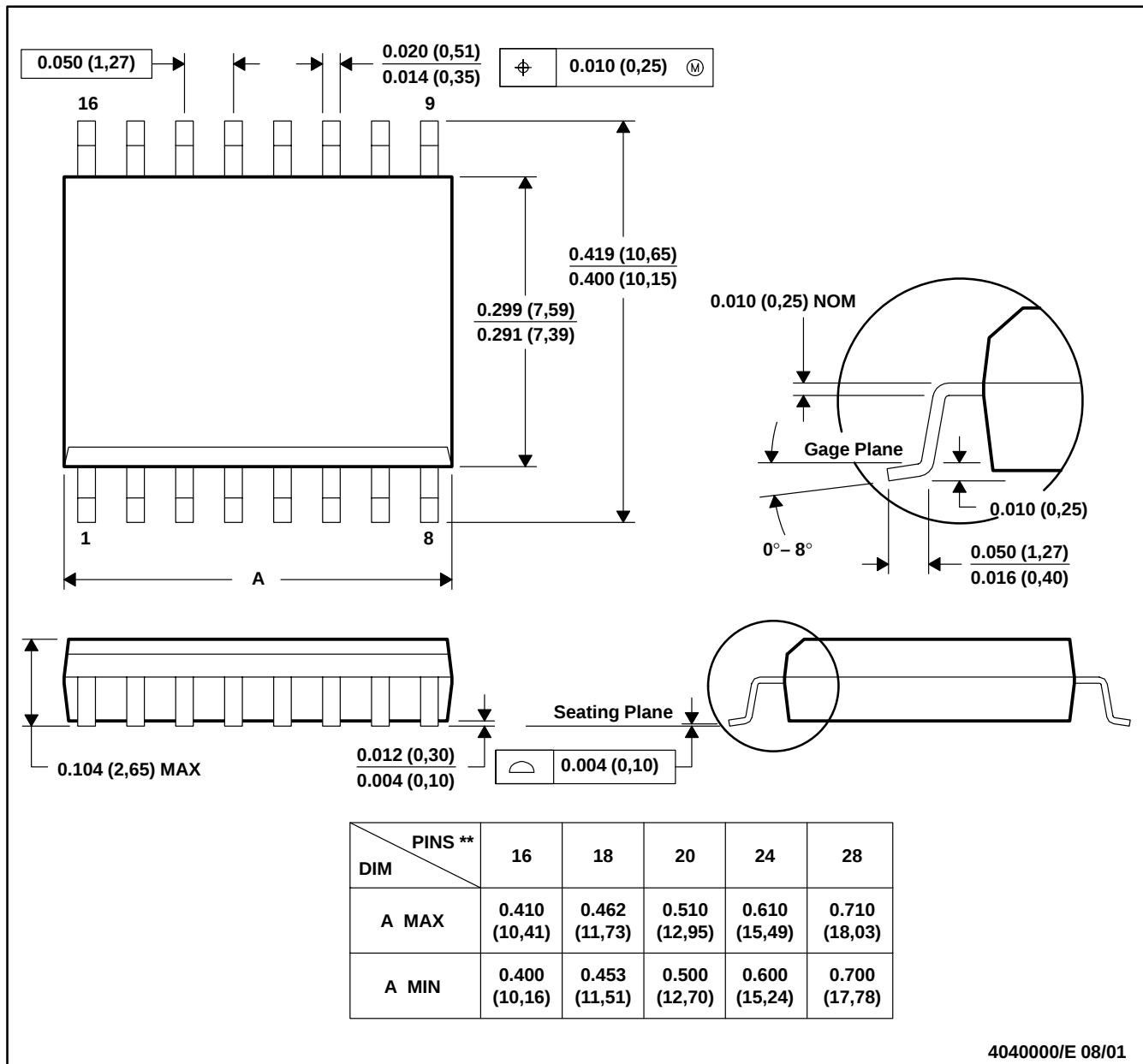


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-013

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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